

Serial No. 09/828,159
Docket No. T36-133137M/KOH

2

AMENDMENTS TO THE CLAIMS:

Claims 1-13 (Canceled)

Claim 14. (Currently Amended) A semiconductor light-emitting apparatus of a flip-chip bonding type, comprising:

a transparent base comprising an inorganic material, which has on one side thereof a first bonding pad and a second bonding pad to be connected to a pair of lead frames with a space between the first and the second bonding pads where a semiconductor light-emitting element is fixed, the light-emitting element comprising:

a light-emitting layer;

a substrate disposed between said light emitting layer and said base; and

E1
a positive electrode comprising a light non-transmissible material, said electrode being disposed on an opposite side of said light-emitting layer from said substrate and reflecting light from said light-emitting layer in a direction through said substrate and said base,

wherein said positive electrode is connected by a bonding wire to a same surface of one of said first and second bonding pads as one of said pair of lead frames.

Claim 15. (Original) A semiconductor light-emitting apparatus of flip chip bonding type as claimed in claim 14, wherein the inorganic material is selected from the group consisting of a SiO₂, sapphire and borosilicate glass.

Claim 16. (Original) A semiconductor light-emitting apparatus of flip chip bonding type as claimed in claim 14, said transparent base is rectangular in its plane view.

Claim 17. (Currently Amended) A semiconductor light-emitting apparatus of flip chip bonding type as claimed in claim 14, wherein the inorganic material comprises has a fluorescent material dispersed therein.

Claim 18. (Currently Amended) A semiconductor light-emitting apparatus of flip chip bonding type as claimed in claim 14, said transparent base comprising a plurality of layers, and at least one of the layers comprising contains a fluorescent material.